



Product Change Notification

Change Notification #: 117008 - 00

Change Title: Intel® Server System R1304WFTYSR, PCN 117008-00, Product Design, Label, Update BIOS/BMC/ME/FRUSDR Firmware System outer box J33994-001 stacking logo update. 1100W Power Supply Add URL to BIS mark

Date of Publication: June 17, 2019

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	July 2, 2019
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R1304WFTYSR:

1. Update BIOS revision to R02.01.0008
2. Update the Manageability Engine (ME) firmware revision to 04.01.04.251
3. Update the Baseboard Management Controller (BMC) firmware revision to 1.93.870cf4f0
4. Update the FRUSDR revision to 1.93

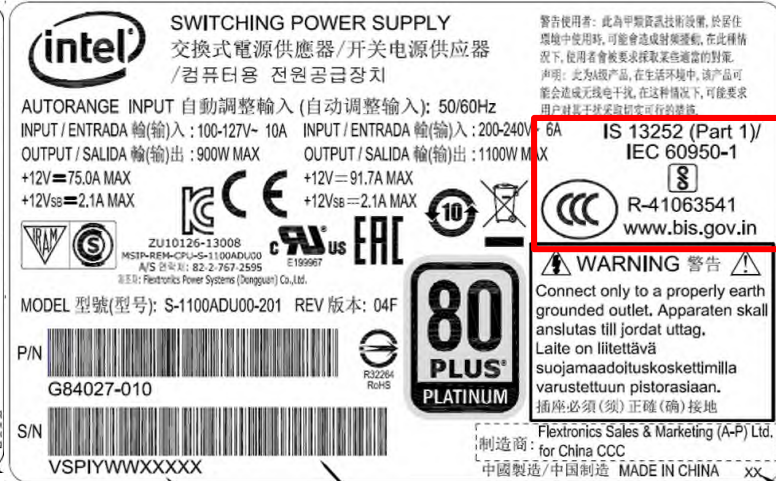
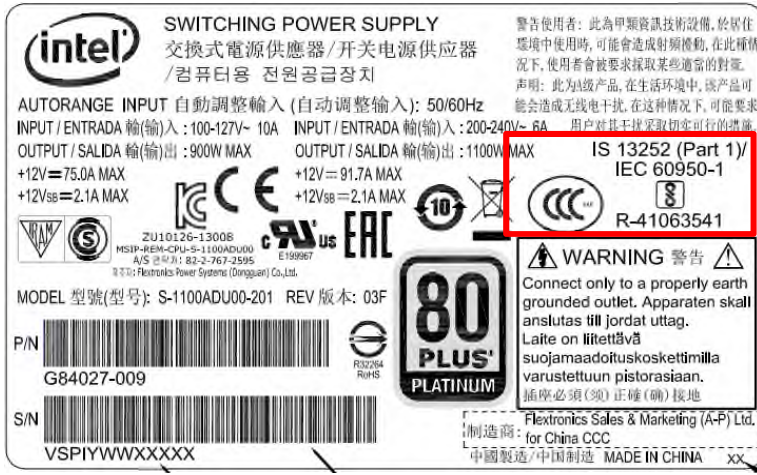
Intel is updating the system outer box stacking logo, original logo mean MAX 7-layers in total, however, only 6-layers as MAX can be supported by logistics racking limitation.

	Original outer box	New outer box
IPN	J33994-001	J33994-002
Description	System outer box with J33994-001 IPN and 6 layers stacking logo printing	Updated system outer box with J33994-002 IPN and 5 layers stacking logo printing
Photos		

Intel is updating the label of the 1100 power supply. The new label includes a URL of the BIS mark and remove "S&E" inside the CCC logo.

Image 1. Power supply label before change

Image 2. Power supply label after change



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
R1304WFTYSR	986048	K39979-001	H48104-871 H48104-881	K39979-002	H48104-872 H48104-882

PCN Revision History:

Date of Revision: June 17, 2019	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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